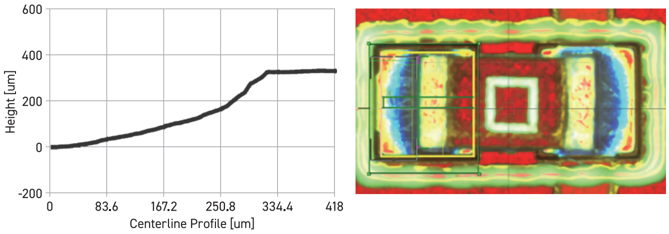
SAKI's New Solder Inspection Solution

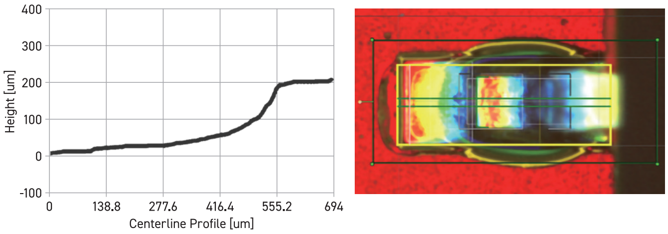
The increase of component miniaturization and high-density PCBs presents a challenge for premium solder quality assurance and IPC-qualified solder inspection. SAKI has risen to meet this challenge with its newly released solder inspection algorithm that both exceeds customer requirements and eliminates the need for complex operator skills for inspection.

New "Fillet Shape" Solder Inspection Algorithm

- High-precision solder inspection for a comprehensive range of component types
- Offers both IPC-compliant and advanced non-wetting inspection
- User-friendly interface enables easy setting of automatic inspection for multiple lead types

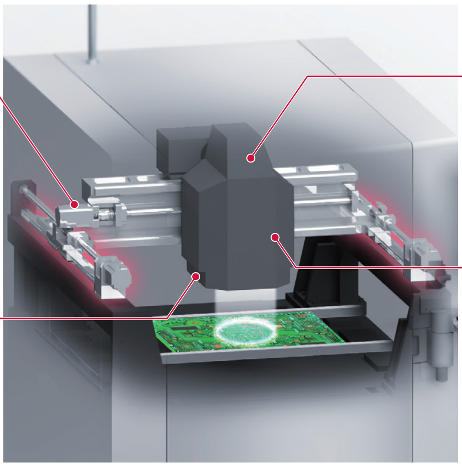


Cross-section of chip solder



Cross-section of IC lead and solder

SAKI's Unique Technology Achieves High-Precision Solder Inspection



Key Feature #1

Rigid Gantry Structure

- Extremely accurate positioning from the dual-motor drive system
- Incredible stopping accuracy with high-resolution linear scale

➡Improved repeatability accuracy for solder measurement inspection

Key Feature #2

Advanced Image Processing Technology

Capable of inspecting the solder measurement of extremely small pads

Key Feature #3

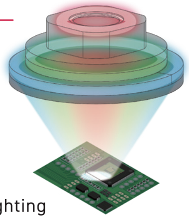
High-resolution Camera

Precision inspection of 0201 components, narrow pitch, and small pads

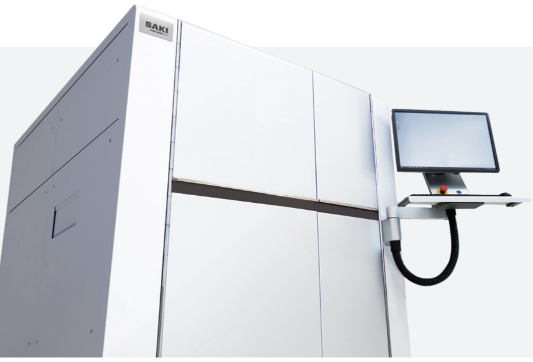
Key Feature #4

Dome Lighting

Improved solder visibility



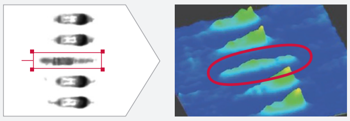
Dome lighting



For manufacturers requiring advanced solder inspection for exceptional quality assurance...

Inline 3D-CT Automated X-ray Inspection System / 3Xi-M110

Pass or fail judgments based on alterations in position, height, width, angle and fillet count, such as IC parts. Fully visualizes back fillets and non-wetting lead fillet shapes.



Non-wetting lead and fillet areas (accumulated)

SAKI
DMG MORI Group

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